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21. (New Claim) The method of claim 20 wherein singulating comprises sawing through the single and continuous encapsulant and the interconnect substrate along the singulation space.

22. (New Claim) The method of claim 20 wherein singulating produces a plurality of packaged semiconductor devices, and further comprising the step of handling each packaged semiconductor device with automated pick and place equipment.

REMARKS

This Preliminary Amendment is being submitted together with the filing of a continuation application under 37 CFR 1.53b. The present application is to be filed as a continuation of co-pending patent application U.S. Serial Number 09/062,986 filed on April 20, 1998. With amendments presented herein, Applicants are canceling original claims 1-13 and adding new claims 14-22. The newly added claims are fully supported by the application as originally filed, and are believed to be patentable over the prior art cited in each of the preceding related applications (copies of which are herein provided together with PTO-1449).

Applicant believes the application is in condition for allowance which action is respectfully solicited. Please contact Applicants attorney identified below if there are any issues regarding this communication or the current Application.

Aug 13, 2001
Date

Respectfully submitted



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REPLACEMENT PARAGRAPHS

On page 1, after the title and before the "Background of the Invention", please insert the following new paragrah:

A1 "This application is a continuation of prior US patent application Serial Number 09//062,986 filed April 20, 1998, which is a divisional application of US Serial Number 08/708296 filed on September 4, 1996."

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